Accepted Manuscript

Effect of applied magnetic field on microstructure of electrodeposited copper

Heather Murdoch, Denise Yin, Efraín Hernández-Rivera, Anit Giri

PII: S1388-2481(18)30248-0

DOI: doi:10.1016/j.elecom.2018.09.013

Reference: ELECOM 6299

To appear in: Electrochemistry Communications

Received date: 6 August 2018
Revised date: 5 September 2018
Accepted date: 24 September 2018

Please cite this article as: Heather Murdoch, Denise Yin, Efraín Hernández-Rivera, Anit Giri, Effect of applied magnetic field on microstructure of electrodeposited copper. Elecom (2018), doi:10.1016/j.elecom.2018.09.013

This is a PDF file of an unedited manuscript that has been accepted for publication. As a service to our customers we are providing this early version of the manuscript. The manuscript will undergo copyediting, typesetting, and review of the resulting proof before it is published in its final form. Please note that during the production process errors may be discovered which could affect the content, and all legal disclaimers that apply to the journal pertain.



ACCEPTED MANUSCRIPT

Effect of applied magnetic field on microstructure of electrodeposited copper

Heather Murdoch^{a*}, Denise Yin^{a,b}, Efraín Hernández-Rivera^a, Anit Giri^a

^a U.S. Army Research Lab, Aberdeen Proving Ground, MD 21005 USA

^b Oak Ridge Associated Universities Postdoctoral Fellow

*corresponding author, heather.a.murdoch.civ@mail.mil

Download English Version:

https://daneshyari.com/en/article/11021414

Download Persian Version:

https://daneshyari.com/article/11021414

<u>Daneshyari.com</u>